

Abstract:

The present invention discloses a technology for a printed wiring board which uses a copper foil without roughening treatment. Therefore, An electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed, comprising a which is sequentially constituted with carrier foil, a bonding interface layer, an electrodeposited copper foil with smooth surfaces surface on both side sides and a resin layer is employed. The resin composition constituting the resin layer is composed of 20 to 80 parts by weight of an epoxy resin which includes and a curing agent, 20 to 80 parts by weight of a solvent soluble aromatic polyamide resin polymer and optionally a curing accelerator in a suitable amount if required.